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Responsible committee: AMT/9 Printed Electronics

Interested committees:

Title: BS IEC 62899-202-13 Printed electronics

Part 202-13: Materials - Resistance measurement method for conductive layer in printed and in-mould electronics

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This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



119/524/CD

COMMITTEE DRAFT (CD)

PROJECT NUMBER: IEC 62899-202-13 ED1	
DATE OF CIRCULATION: 2024-12-13	CLOSING DATE FOR COMMENTS: 2025-02-07
SUPERSEDES DOCUMENTS: 119/492/NP, 119/517/RVN	

IEC TC 119 : PRINTED ELECTRONICS	
SECRETARIAT: Korea, Republic of	SECRETARY: Mr Kyung-Tae Kang
OF INTEREST TO THE FOLLOWING COMMITTEES: TC 91	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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TITLE: IEC 62899-202-13 ED1 Printed electronics - Part 202-13: Materials - Resistance measurement method for conductive layer in printed and in-mould electronics

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED ELECTRONICS

Part 202-13: Materials – Resistance measurement method for conductive layer in printed and in-mould electronics

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IEC 62899-202-XX has been prepared by of IEC technical committee 119: Printed Electronics.
It is an International Standard.

The text of this International Standard, is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard, is English.